



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Etsuko NAKAMURA et al. :
Serial No. 10/721,164 : **Attn: APPLICATION BRANCH**
Filed November 26, 2003 : Attorney Docket No. 2003_1698A

LOWER LAYER MATERIAL FOR :
WIRING, EMBEDDED MATERIAL, : **Confirmation No. 5528**
AND WIRING FORMATION METHOD :

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In the interest of compact prosecution, please amend the present application as follows: